

IN THE SPECIFICATION

Please replace the following paragraphs of the specification. Applicant includes herewith an Attachment for Specification Amendments showing a marked up version of each replacement paragraph.

Please amend the title as follows:

"Semiconductor Device Having a Flat Protective Adhesive Sheet"

On Page 7, replace the paragraph on lines 17 through 24 with the following paragraph:

C1
The first adhesive sheet 2 is fixed a flat plate 4 show in FIG. 1B at a side opposite to the adhesive 2b. Specifically, the first adhesive sheet 2 is fixed to the plate 4 by vacuum attraction performed by a vacuum chuck stage (not shown), which is disposed under the plate 4, via a through hole 4a defined in an edge portion of the plate 4. Accordingly, even when the first adhesive sheet 2 is charged, static electricity is removed through the plate 4 having conductivity.

IN THE CLAIMS

The currently pending claims are also listed below.

1. (Pending) A semiconductor device comprising:
 - a semiconductor wafer having a structure portion exposed on a surface thereof; and
 - an adhesive sheet detachably attached to the surface of the semiconductor wafer and covering the structure portion, the adhesive sheet